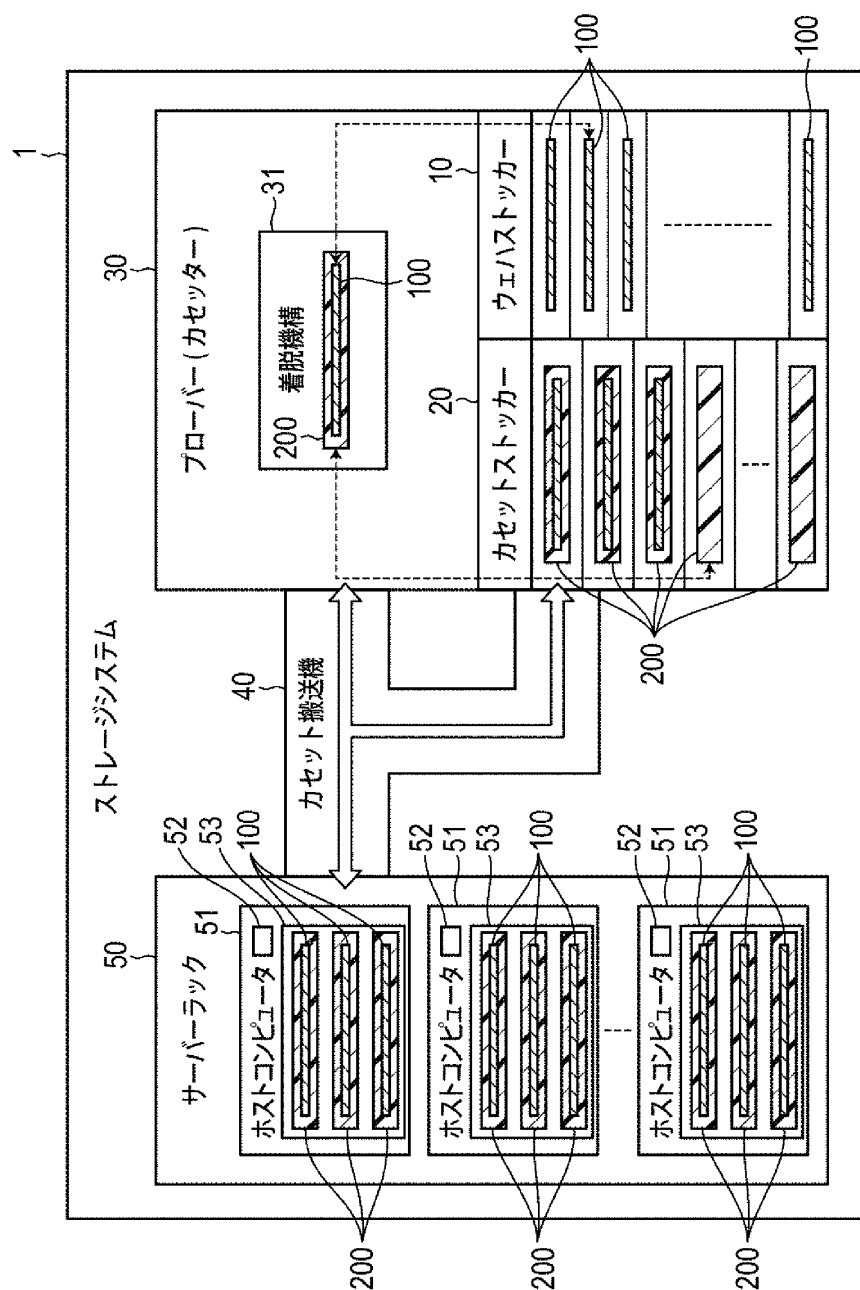
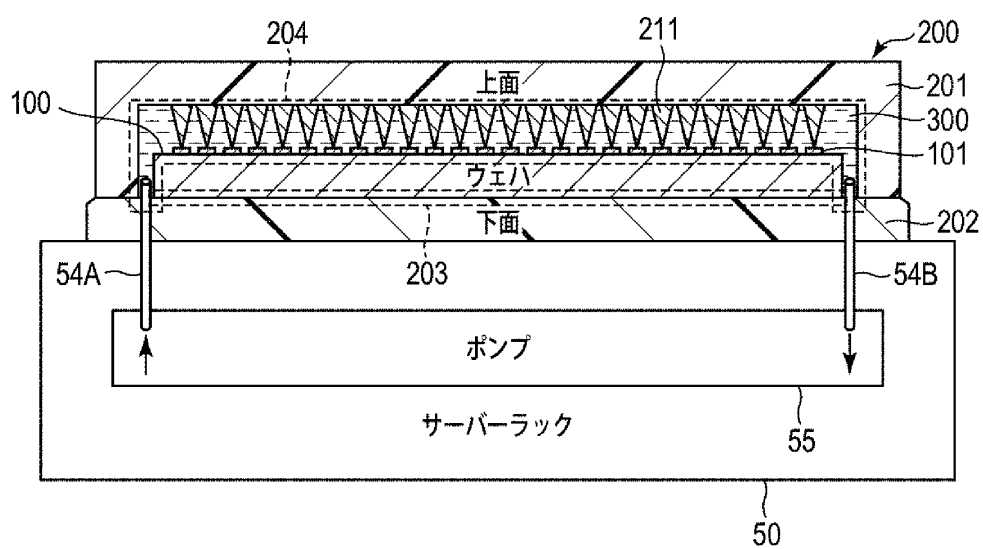
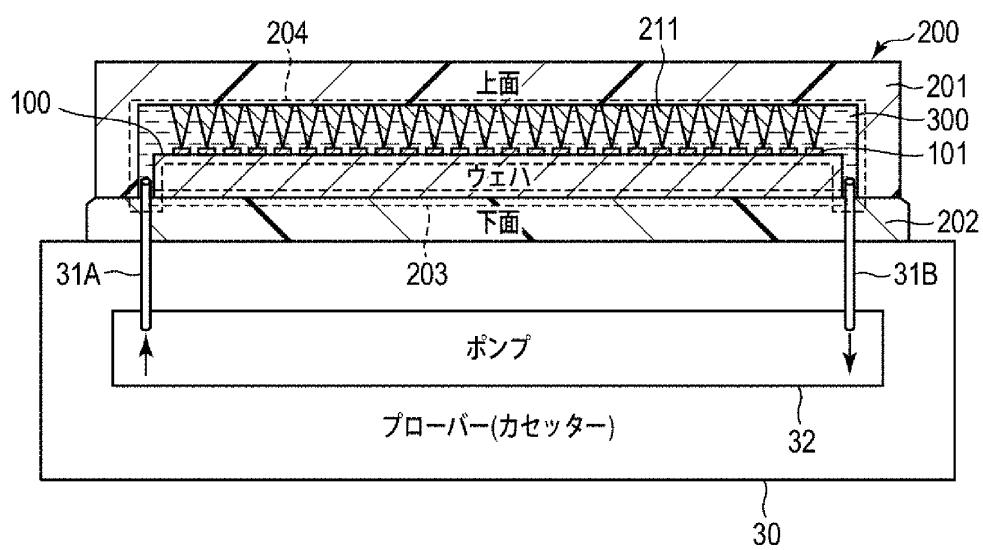
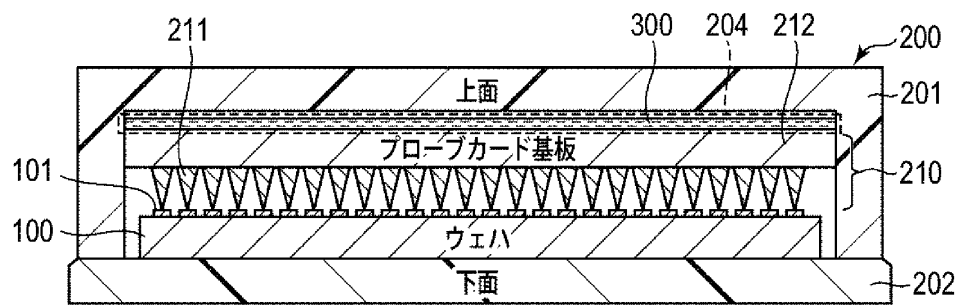


[図1]

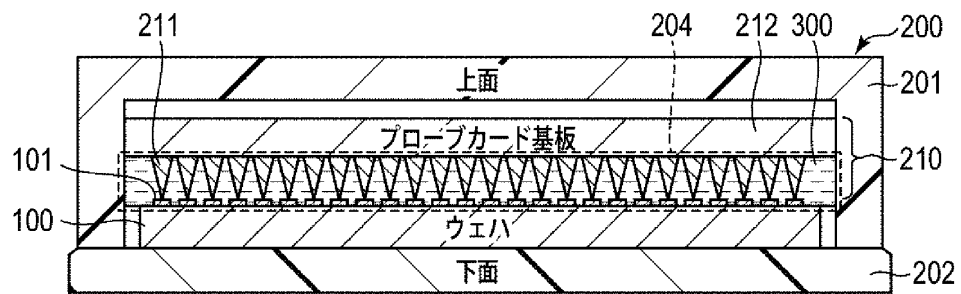




[図4]



[図5]



[図6]

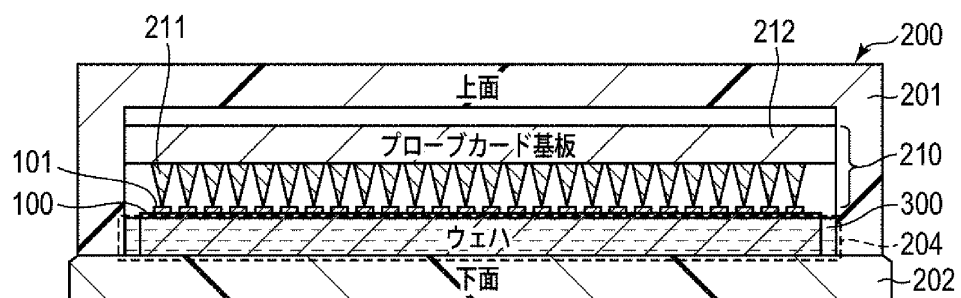
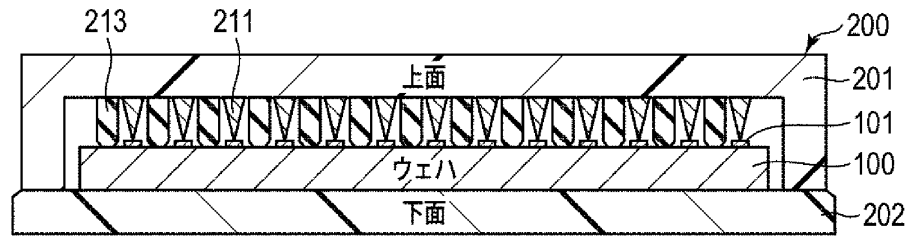


Figure 1 is a schematic cross-sectional view of a probe card assembly. The assembly includes a top layer (33), a probe card substrate (プローブカード基板), a wafer (ウェハ), and a bottom layer (32). The probe card substrate is connected to the wafer via a series of probes (101) and a contact pad (100). The wafer is labeled with "上面" (top surface) and "下面" (bottom surface). The probe card substrate is labeled with "200" and "212". The wafer is labeled with "210" and "201". The bottom layer is labeled with "202". The entire assembly is housed in a container (300). Below the container, there is a pump (ポンプ) connected to two tubes (31A and 31B) that circulate fluid through the assembly.

[図9]



[図10]

